

POWER SCHOTTKY RECTIFIER

MAIN PRODUCT CHARACTERISTICS

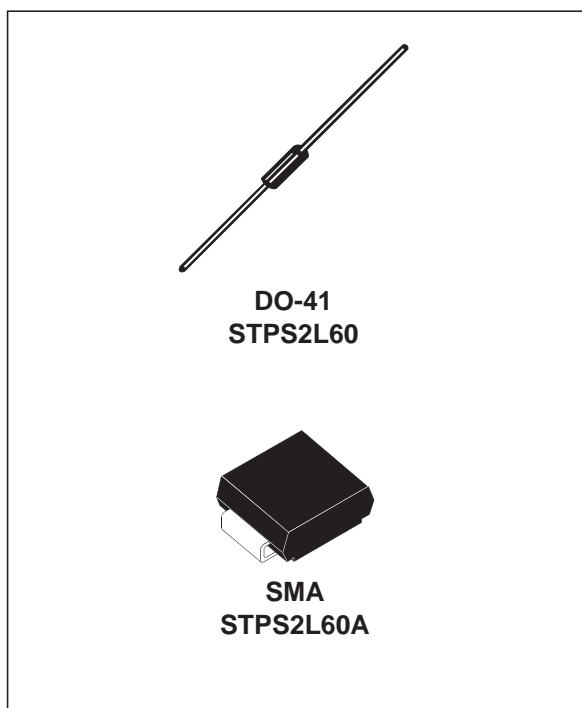
$I_{F(AV)}$	2 A
V_{RRM}	60 V
$T_j(max)$	150°C
$V_F(max)$	0.55 V

FEATURES AND BENEFITS

- NEGLIGIBLE SWITCHING LOSSES
- LOW FORWARD VOLTAGE DROP

DESCRIPTION

Axial and Surface Mount Power Schottky rectifier suited for Switch Mode Power Supplies and high frequency DC to DC converters. Packaged in DO-41 and SMA, this device is intended for use in low voltage, high frequency inverters and small battery chargers.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		60	V
$I_{F(RMS)}$	RMS forward current		10	A
$I_{F(AV)}$	Average forward current	$T_L = 115^\circ\text{C} \quad \delta = 0.5$ SMA	2	A
		$T_L = 110^\circ\text{C} \quad \delta = 0.5$ DO-41		
I_{FSM}	Surge non repetitive forward current	$t_p = 10 \text{ ms}$ Sinusoidal	75	A
T_{stg}	Storage temperature range		- 65 to + 150	°C
T_j	Maximum junction temperature *		150	°C
dV/dt	Critical rate of rise of reverse voltage		10000	V/ μs

* : $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ thermal runaway condition for a diode on its own heatsink

STPS2L60/A

THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-l)}$	Junction to leads	Lead length = 10 mm	DO-41	30
			SMA	25

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
I_R^*	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = 60\text{V}$			0.1	mA
		$T_j = 100^\circ\text{C}$			2	10	
V_F^*	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 2\text{A}$			0.60	V
		$T_j = 125^\circ\text{C}$			0.51	0.55	
		$T_j = 25^\circ\text{C}$	$I_F = 4\text{A}$			0.77	
		$T_j = 125^\circ\text{C}$			0.62	0.67	

Pulse test : * $t_p = 380\ \mu\text{s}$, $\delta < 2\%$

To evaluate the maximum conduction losses use the following equation:

$$P = 0.43 \times I_{F(AV)} + 0.06 \times I_{F(RMS)}^2$$

Fig. 1: Average forward power dissipation versus average forward current.

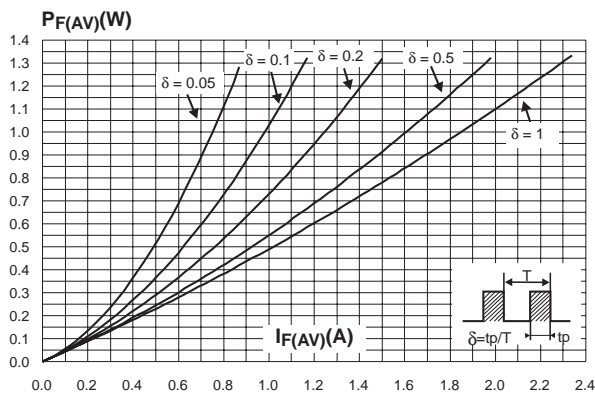


Fig. 2: Average forward current versus ambient temperature ($\delta = 0.5$).

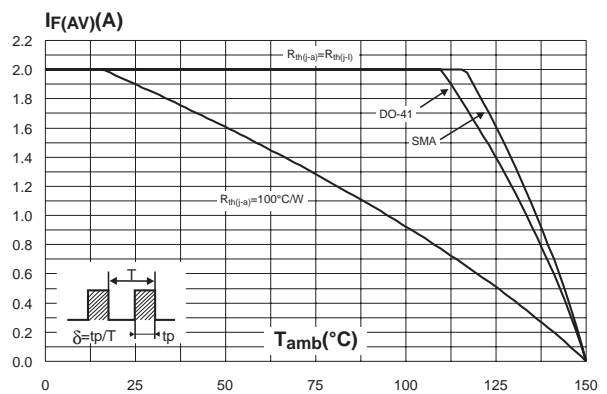


Fig. 3-1: Non repetitive surge peak forward current versus overload duration (maximum values) (DO-41).

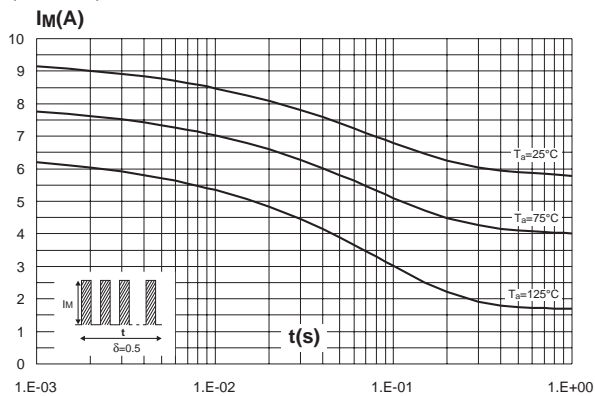


Fig. 3-2: Non repetitive surge peak forward current versus overload duration (maximum values) (SMA).

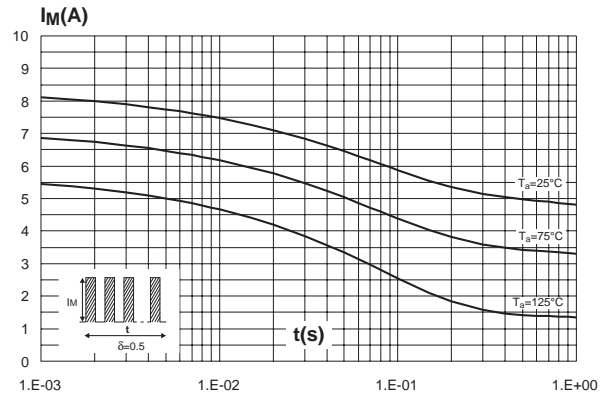


Fig. 4-1: Relative variation of thermal impedance junction to ambient versus pulse duration (DO-41).

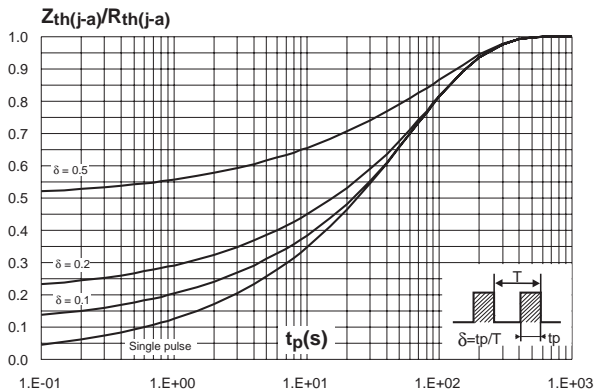


Fig. 4-2: Relative variation of thermal impedance junction to ambient versus pulse duration (SMA).

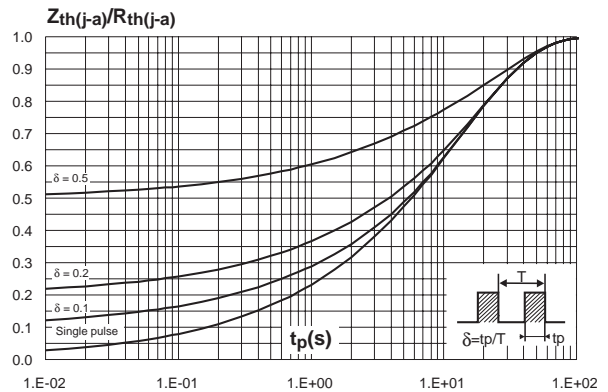


Fig. 5: Reverse leakage current versus reverse voltage applied (typical values).

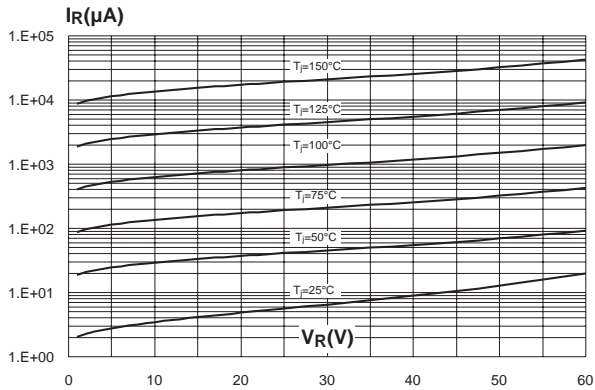


Fig. 6: Junction capacitance versus reverse voltage applied (typical values).

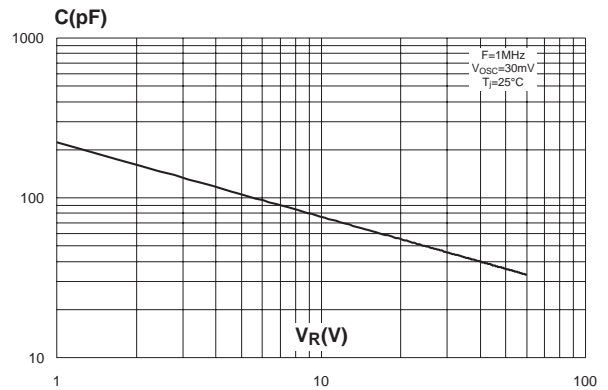


Fig. 7: Forward voltage drop versus forward current (low level, maximum values).

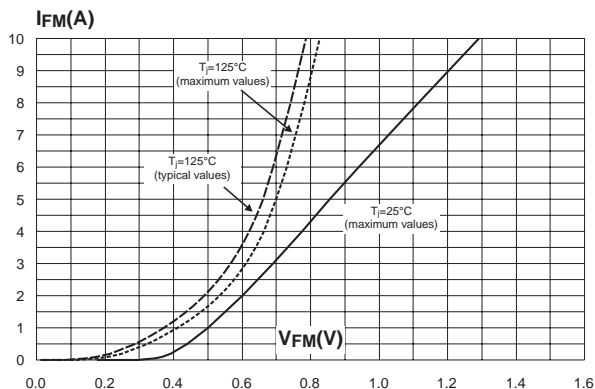
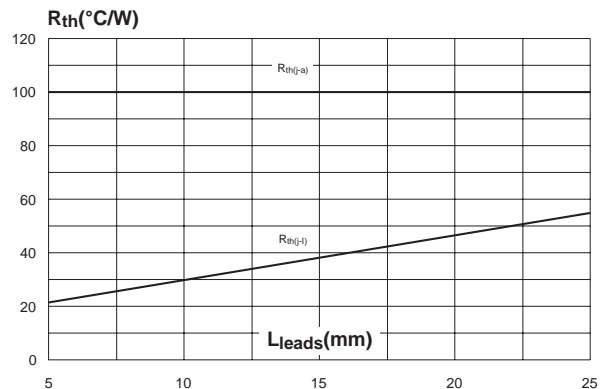


Fig. 8: Thermal resistance versus lead length (DO-41).



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Fig. 9-1: Thermal resistance junction to ambient versus copper surface under each lead (Epoxy printed circuit board FR4, Cu: 35µm) (SMA).

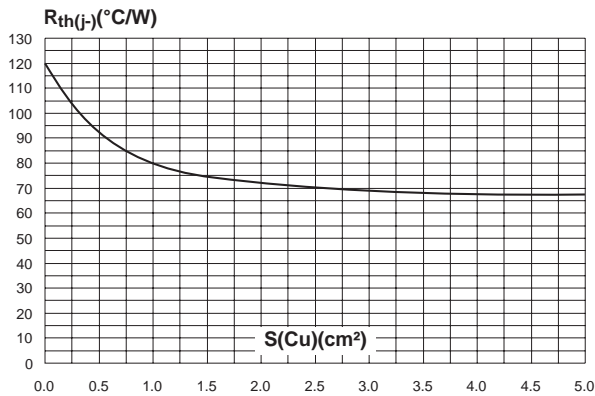
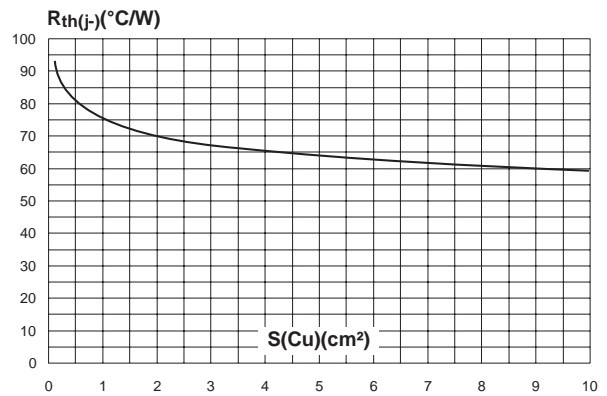


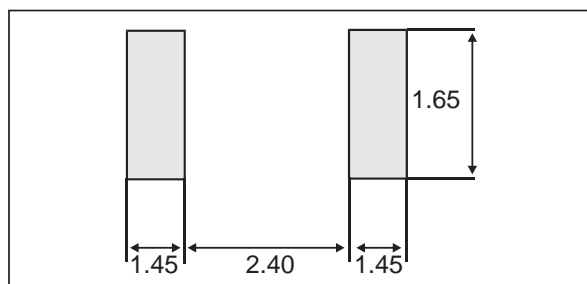
Fig. 9-2: Thermal resistance junction to ambient versus copper surface under each lead (Epoxy printed circuit board FR4, Cu: 35µm) (DO-41).



PACKAGE MECHANICAL DATA SMA (JEDEC DO-214AC)

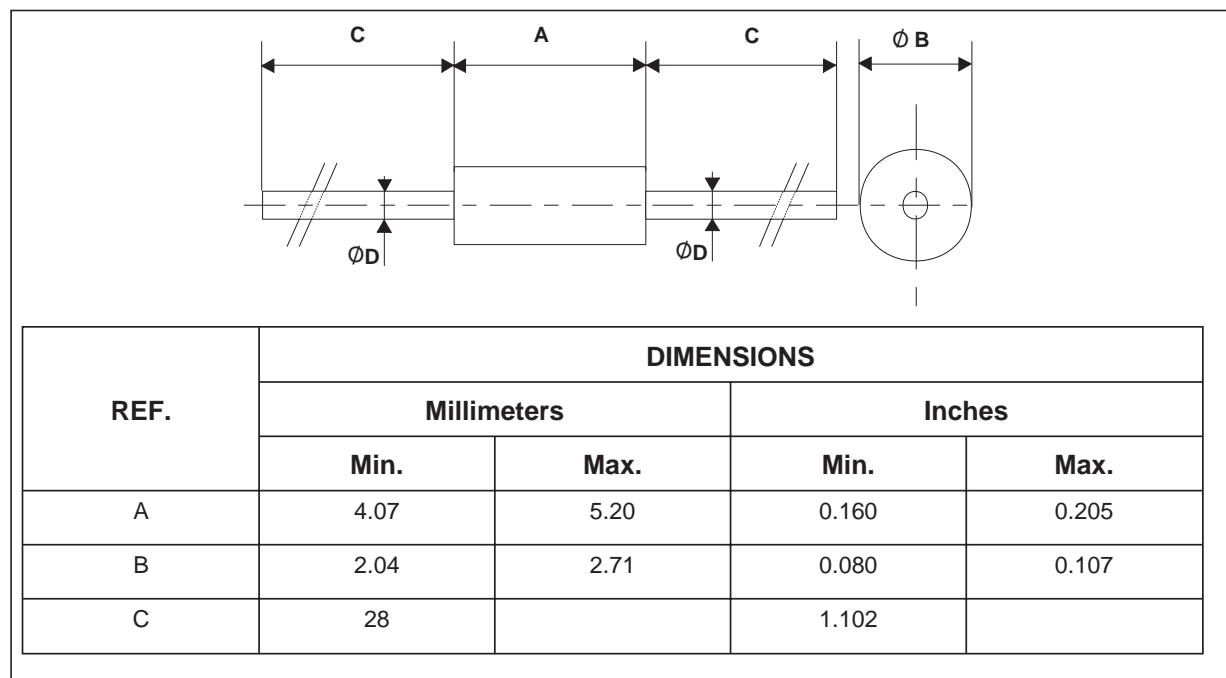
REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.70	0.075	0.106
A2	0.05	0.20	0.002	0.008
b	1.25	1.65	0.049	0.065
c	0.15	0.41	0.006	0.016
E	4.80	5.60	0.189	0.220
E1	3.95	4.60	0.156	0.181
D	2.25	2.95	0.089	0.116

FOOT PRINT DIMENSIONS (in millimeters)



PACKAGE MECHANICAL DATA

DO-41 plastic



Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS2L60	STPS2L60	DO-41	0.34g	2000	Ammopack
STPS2L60RL	STPS2L60	DO-41	0.34g	5000	Tape & Reel
STPS2L60A	S26	SMA	0.068 g	5000	Tape & Reel

- Epoxy meets UL94,V0

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